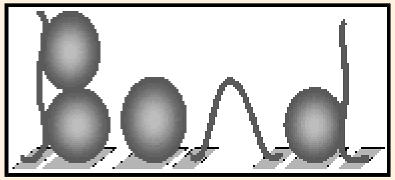

Workshop on Bonding and Die Attach Technologies

11-12 June 2003 at CERN, Geneva, Switzerland

http://cern.ch/ssd/bond

The scope of this workshop spans

- **wire and TAB bonding,**
- **bump bonding,**
- **gluing techniques,**
- **methods to assess the bond quality.**

The workshop will review the bonding techniques, currently applied to detector construction, and try to estimate their technological prospects. The participation of companies, being involved in the fabrication of PCBs, hybrids, pitch adapters or wire and bump bonds is highly welcome.

An equally important goal is to provide a platform for exchanging knowledge and practical experience between the various institutes and detector collaborations. The active participation of technicians and bond operators is considered as particularly valuable.

The workshop will take place at CERN 11-12 June 2003 in room 40-SS-C01 in building 40

Organizers: A.Honma, C. Joram, I.Mcgill, M.Moll, P.Riedler (CERN)

Registration (free of charge) on http://cern.ch/ssd/bond/